

Product Change Notification / JAON-04IGFH099

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15-Sep-2023

Product Category:

Power MOSFET Drivers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4542 Cancellation Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8900NC die attach and gold (Au) bond wire material assembled at MMT assembly site.

Affected CPNs:

JAON-04IGFH099_Affected_CPN_09152023.pdf JAON-04IGFH099_Affected_CPN_09152023.csv

Notification Text:

PCN Status: Cancellation Notification

Microchip Parts Affected: This change would have affected selected products available in 8L SOIC package.

Description of Change:This qualification was originally performed to qualify new lead frame design for selected products available in 8L SOIC package using 8900NC die attach and gold (Au) bond wire material assembled at MMT assembly site.

Impacts to Data Sheet:Not applicable

Change Impact: Not applicable

Reason for ChangeMicrochip has decided to not qualify new lead frame design for selected products available in 8L SOIC package using 8900NC die attach and gold (Au) bond wire material assembled at MMT assembly site.

Change Implementation Status: Not applicable

Estimated Qualification Completion Date: Not applicable
Revision History: February 9, 2021: Issued initial notification. September 15, 2023: Issued cancellation notification.
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Affected Catalog Part Numbers (CPN)

MCP1407-E/SN

MCP1407T-E/SN

TC1410COA

TC1410EOA

TC1410EOA713

TC1410COA713

TC1411COA

TC1411VOA

TC1411EOA

TC1411EOA713

TC1411COA713

TC1411VOA713

TC1411NCOA

TC1411NVOA

TC1411NEOA

1C1+1111LO11

TC1411NEOA713

TC1411NCOA713

TC1411NVOA713

TC1412NCOA

TC1412NEOA

TC1412NEOA713

TC1412NCOA713

TC1413NCOA

TC1413NEOA

TC1413NEOA713

TC1413NCOA713

TC4420COA

TC4420VOA

TC4420EOA

TC4420EOA713

TC4420COA713

TC4420VOA713

TC4429COA

TC4429VOA

TC4429EOA

TC4429EOAAAC

TC4429EOA713

TC4429COA713

TC4429VOA713

Date: Thursday, September 14, 2023